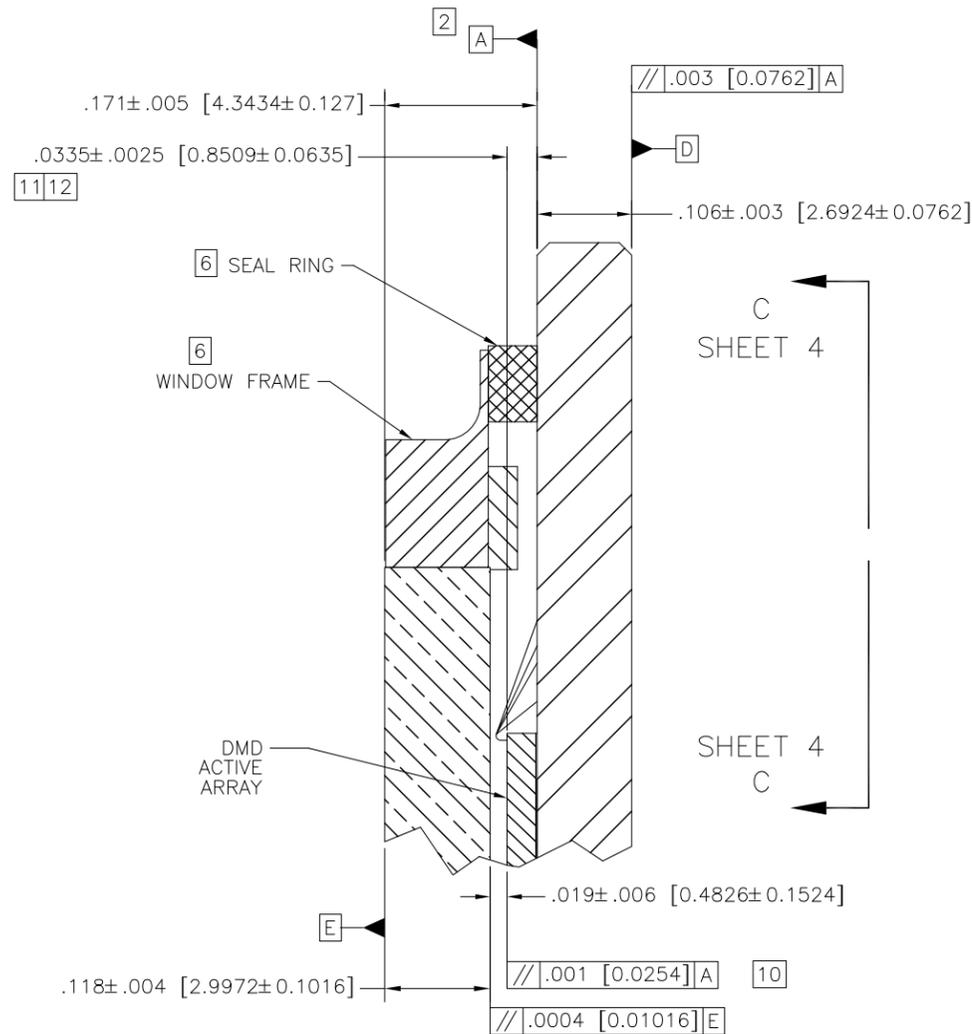
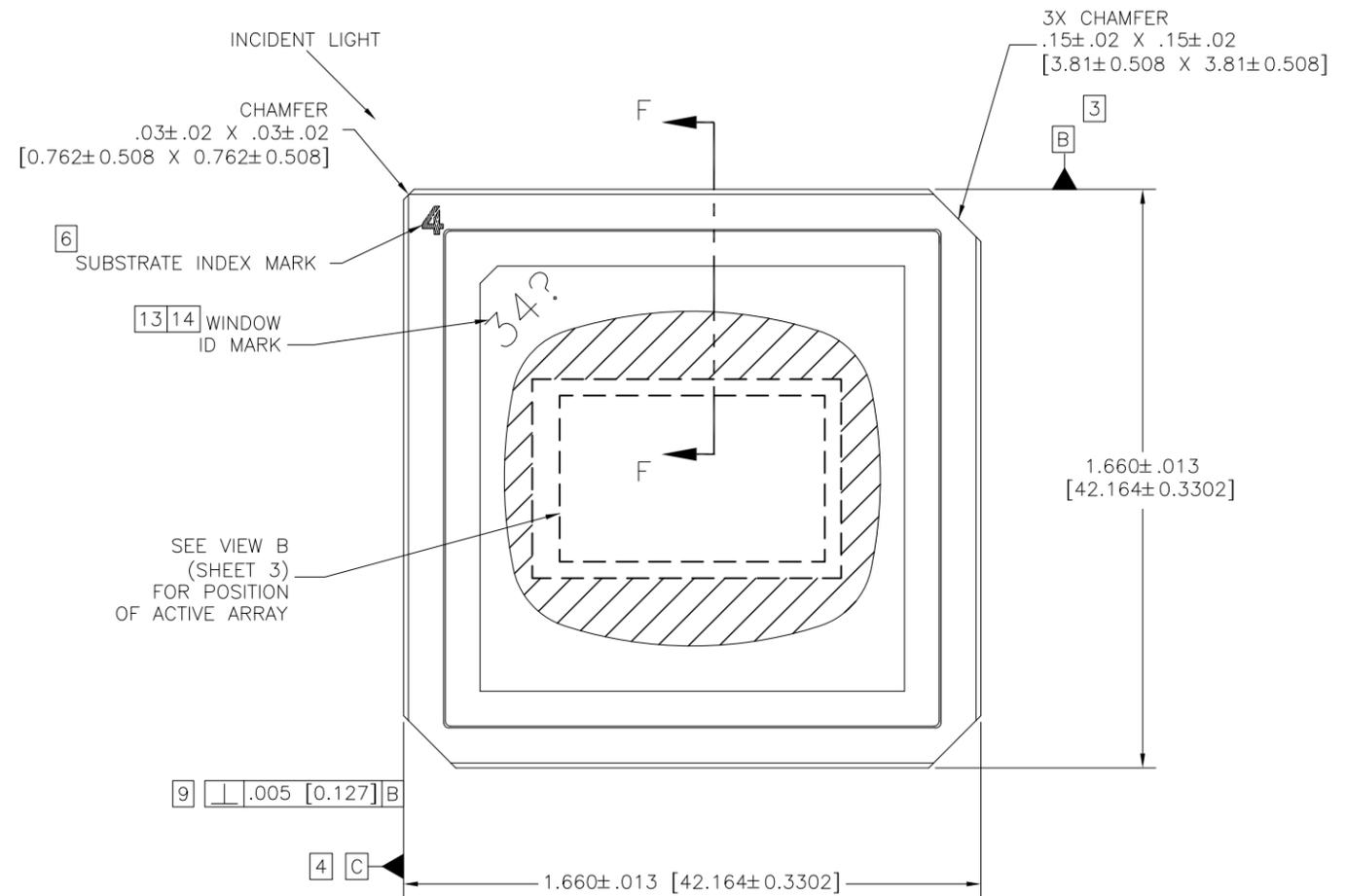


REV	DESCRIPTION	DATE	APPROVED
A	ECO 2098262, INITIAL RELEASE	4/16/09	M. AVERY
B	ECO 2099196, CHANGE DESIGN TO OVAL WINDOW	5/22/09	M. AVERY

NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994.
- 2 DATUM A (SYSTEM INTERFACE PLANE) ESTABLISHED BY THREE DATUM AREAS SHOWN IN VIEW A (SHEET 2).
- 3 DATUM B ESTABLISHED BY TWO DATUM AREAS SHOWN IN VIEW A (SHEET 2).
- 4 DATUM C ESTABLISHED BY DATUM AREA SHOWN IN VIEW A (SHEET 2).
- 5 LOCALIZED BACKSIDE SURFACE FLATNESS APPLIES TO ENTIRE SURFACE.
- 6 SUBSTRATE INDEX MARK, BACK INDEX PAD, SYMBOLIZATION PAD, SEAL RING, AND WINDOW FRAME TO BE ELECTRICALLY CONNECTED TO VSS PLANE IN SUBSTRATE.
- 7 THE DIMENSIONS OF THE SYMBOLIZATION PAD REPRESENT THE APPROXIMATE SIZE AND LOCATION OF THE RECOMMENDED THERMAL INTERFACE AREA.
- 8 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND IS THE MAXIMUM VALUE ALLOWED.
- 9 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE.
- 10 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY.
- 11 DIE HEIGHT TOLERANCE APPLIES TO CENTER OF DMD ACTIVE ARRAY ONLY.
- 12 DMD ACTIVE ARRAY ROTATION AND LOCATION DIMENSIONS ARE RELATED TO DATUM A (PRIMARY), DATUM B (SECONDARY), AND DATUM C (TERTIARY).
- 13 WINDOW SHALL BE ORIENTED SUCH THAT I.D. MARK ALIGNS WITH SUBSTRATE INDEX MARK AS SHOWN.
- 14 ? IS A WILD CARD CHARACTER AND CAN BE ANY LETTER.



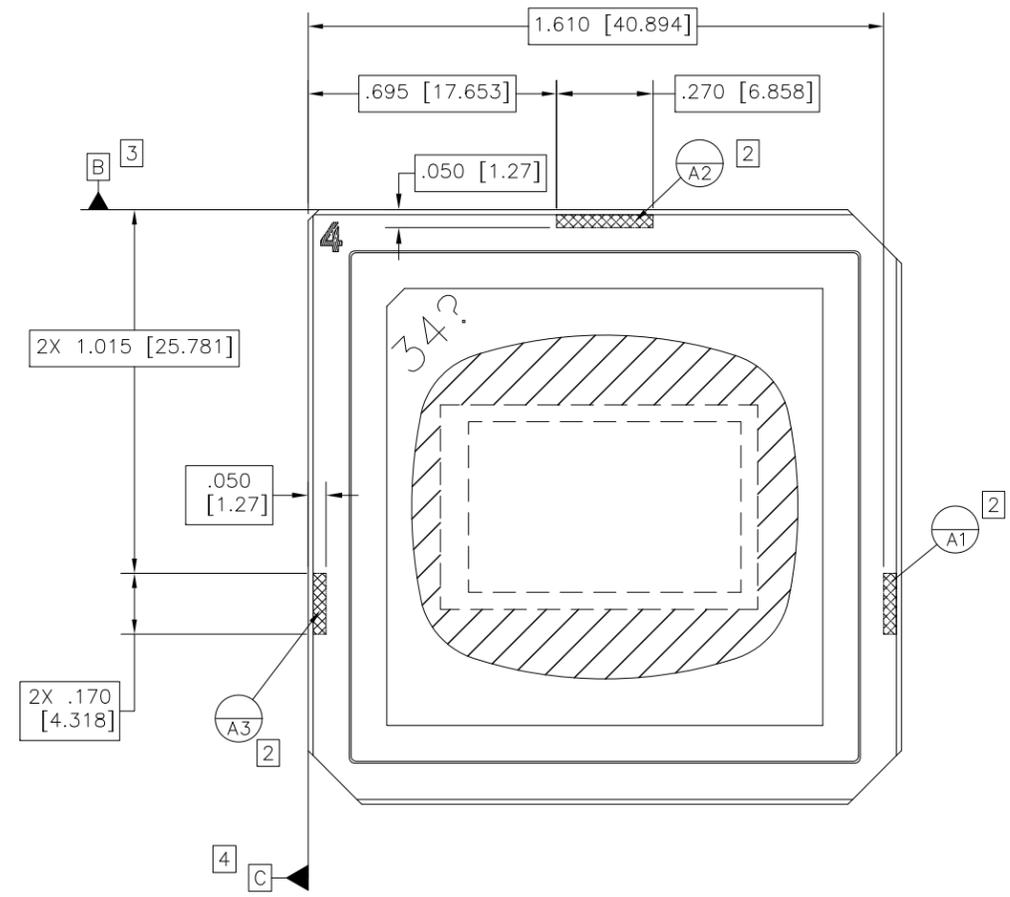
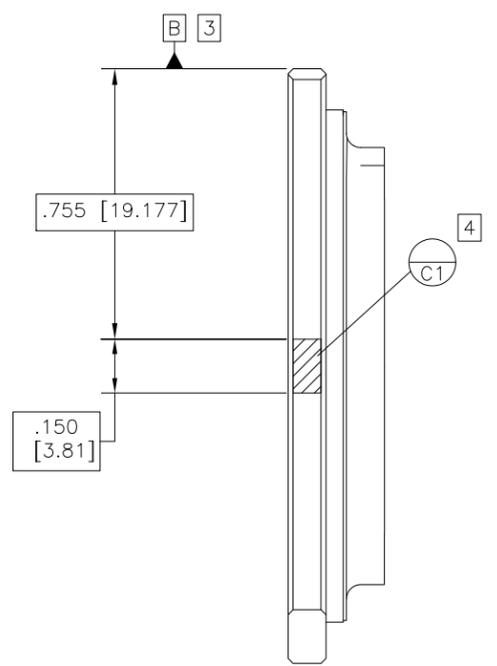
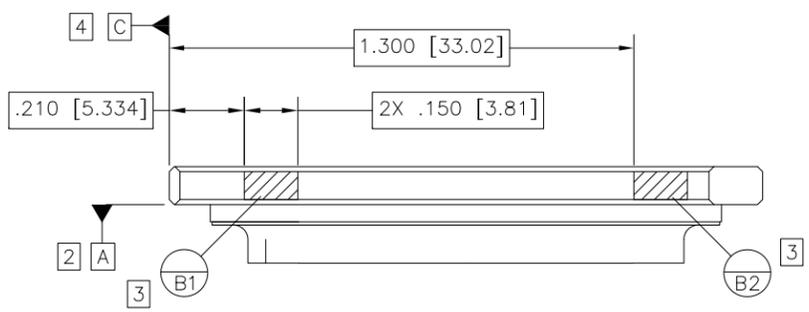
SECTION F-F
SCALE 10/1

-1	ITEM	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES
QTY	NO			

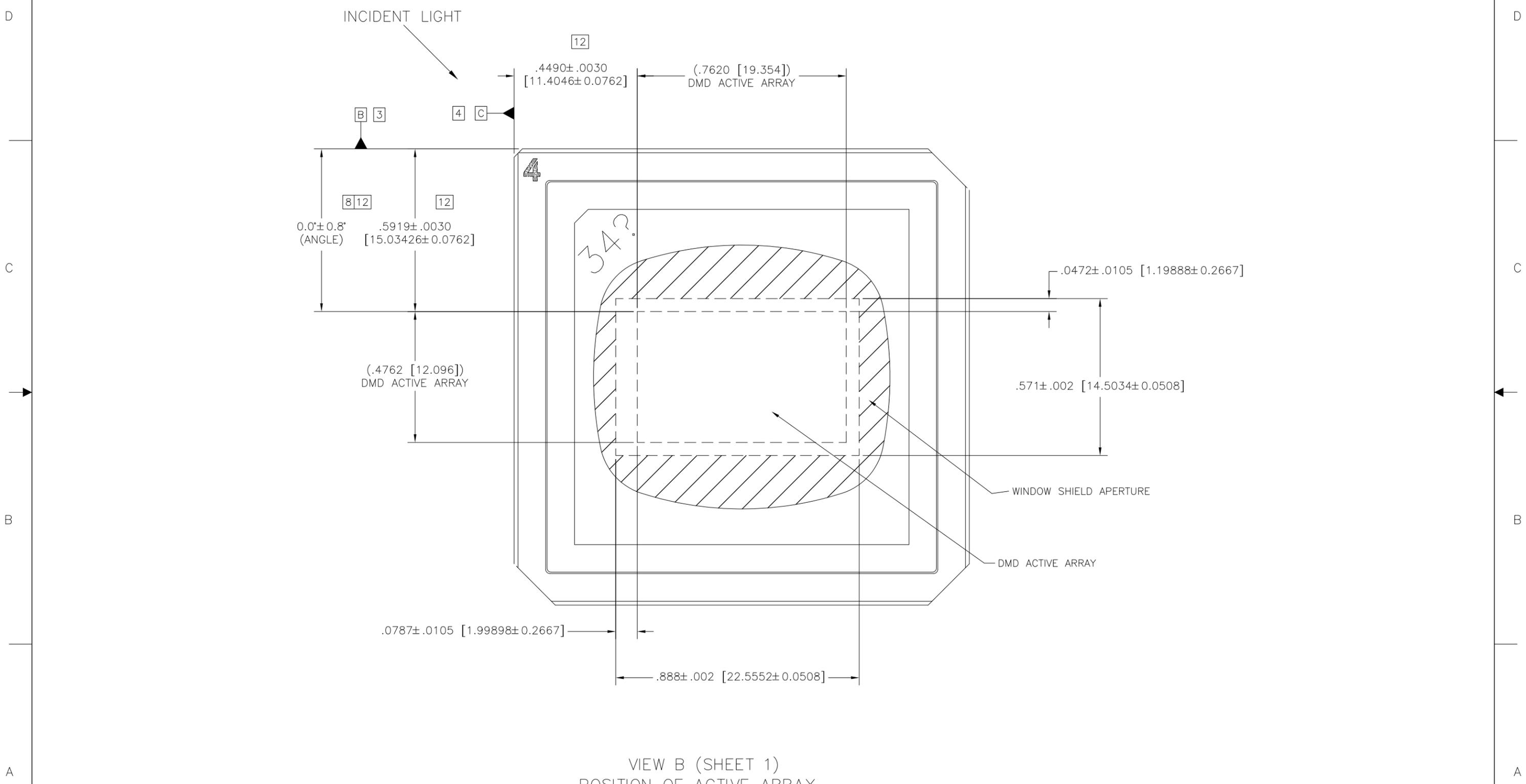
UNLESS OTHERWISE SPECIFIED		PARTS LIST	
• DIMENSIONS ARE IN INCHES[MILLIMETERS]		DWN	M. AVERY DATE 4/02/09
• TOLERANCES: ANGLES ± 1°		ENGR	M. AVERY 4/02/09
3 PLACE DECIMALS ± .005[0.127]		QA	
2 PLACE DECIMALS ± .01[0.254]		APVD	
• REMOVE ALL BURRS AND SHARP EDGES		SIZE	D
• CONCENTRICITY MACHINED DIAMETERS .010 FIM		DRAWING NO	2510425
• DIMENSIONAL LIMITS APPLY BEFORE PROCESSES		SCALE	4/1
• PARENTHETICAL INFO FOR REF ONLY		SHEET	1 OF 4
HOLE TOLERANCE		REV	B
.013 THRU +.004	.126 THRU +.005		
.126 THRU -.001	.251 THRU -.001		
.501 THRU +.008	.751 THRU +.010		
.750 THRU -.001	1.000 THRU -.001		
THRU ANGLE PROJECTION	NONE	APPLICATION	USED ON
	0314DA		



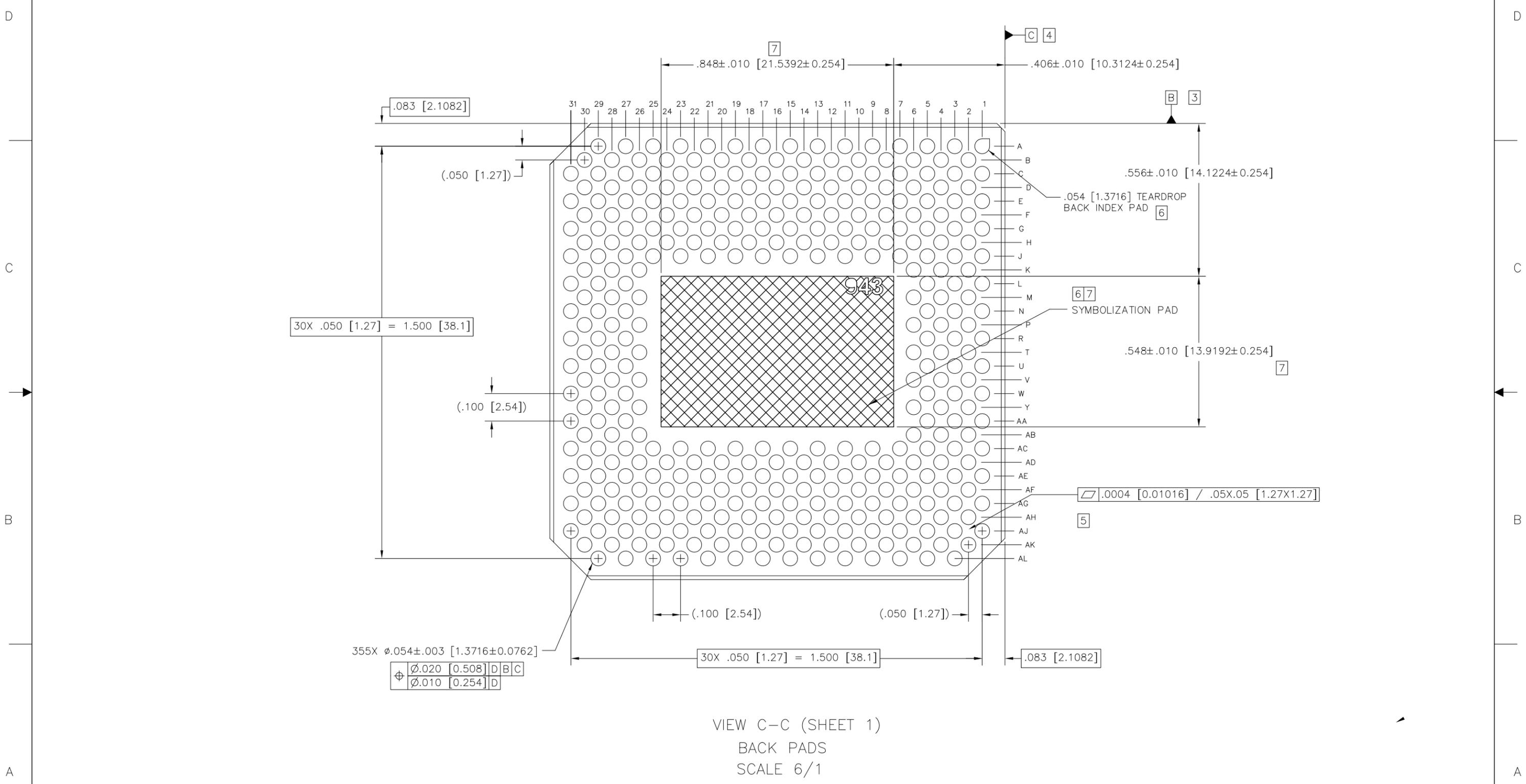
ICD, MECHANICAL, DMD
.9" WQXGA 2XLVDS TYPE A



VIEW A (SHEET 1 NOTES)
 DATUM A, B AND C DETAILS



VIEW B (SHEET 1)
POSITION OF ACTIVE ARRAY
SCALE 6/1



VIEW C-C (SHEET 1)
BACK PADS
SCALE 6/1

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